

101.6mm (4.0 INCH) 5x7 DOT MATRIX DISPLAY

Part Number: TC40-11SURKWA Hyper Red

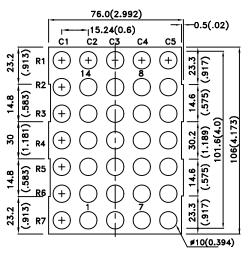
Features

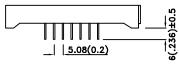
- 4.0 inch matrix height.
- Dot size 10mm.
- Low current operation.
- High contrast and light output.
- Stackable horizontally.
- Easy mounting on p.c. boards or sockets.
- Multicolor available.
- Mechanically rugged.
- Standard : gray face, white dot.
- RoHS compliant.

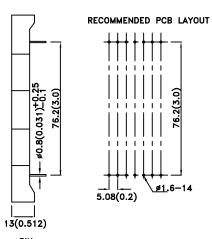
Description

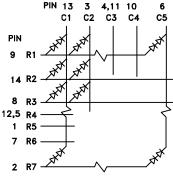
The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram













Notes

- 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
- 2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAB7849 APPROVED: WYNEC REV NO: V.7A CHECKED: Joe Lee DATE: MAY/07/2013 DRAWN: Y.Liu PAGE: 1 OF 6 ERP: 1332000682

Selection Guide

Part No.	Dice	Lens Type	lv (ucd) [1] @ 10mA		Description
			Min.	Тур.	•
TC40-11SURKWA	Hyper Red (AlGalnP)	White Diffused	88000	240000	Column Cathode
			*31000	*70000	

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	645		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance (Per Chip)	Hyper Red	35		pF	V _F =0V;f=1MHz
VF [2]	Forward Voltage (Per Dot)	Hyper Red	3.9	5.0	V	IF=20mA
lR	Reverse Current (Per Dot)	Hyper Red		10	uA	V _R =10V

Notes:

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

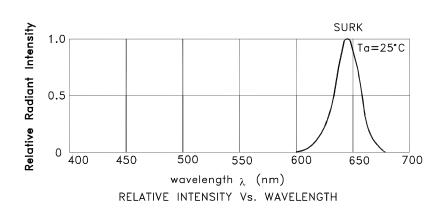
Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units		
Power dissipation (Per Dot)	150	mW		
DC Forward Current (Per Dot)	30	mA		
Peak Forward Current [1] (Per Dot)	185	mA		
Reverse Voltage (Per Dot)	5	V		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature[2]	260°C For 3-5 Seconds			

- Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base.

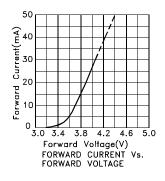
SPEC NO: DSAB7849 **REV NO: V.7A** DATE: MAY/07/2013 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: Y.Liu ERP: 1332000682

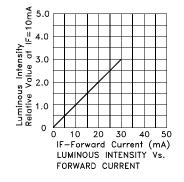
^{1.} Luminous intensity/ luminous Flux: +/-15%.
*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

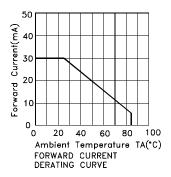


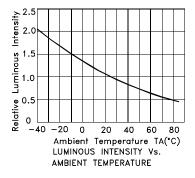
Hyper Red

TC40-11SURKWA

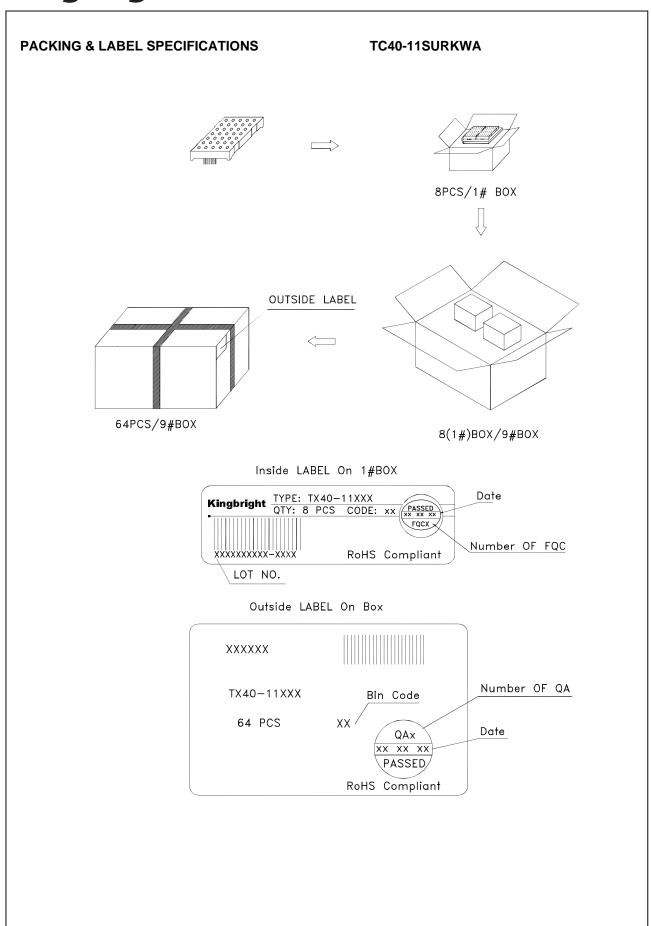








SPEC NO: DSAB7849 APPROVED: WYNEC REV NO: V.7A CHECKED: Joe Lee DATE: MAY/07/2013 DRAWN: Y.Liu PAGE: 3 OF 6 ERP: 1332000682

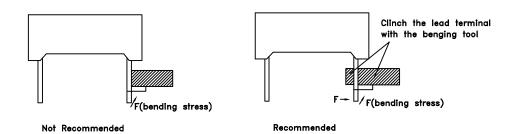


SPEC NO: DSAB7849 APPROVED: WYNEC REV NO: V.7A CHECKED: Joe Lee DATE: MAY/07/2013 DRAWN: Y.Liu PAGE: 4 OF 6 ERP: 1332000682

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

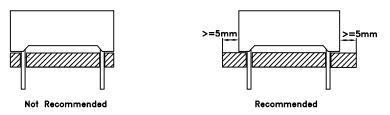


Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



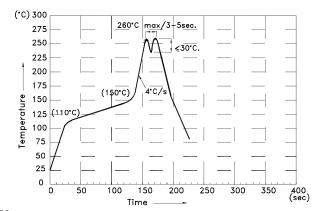
3.The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



SPEC NO: DSAB7849 APPROVED: WYNEC REV NO: V.7A CHECKED: Joe Lee DATE: MAY/07/2013 DRAWN: Y.Liu PAGE: 5 OF 6 ERP: 1332000682

DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top—surface temperature should be kept below 105°C 5.No more than once.

Soldering General Notes:

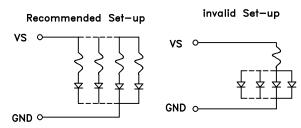
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



Detailed application notes are listed on our website. http://www.kingbright.com/application_notes

SPEC NO: DSAB7849 REV NO: V.7A DATE: MAY/07/2013 PAGE: 6 OF 6
APPROVED: WYNEC CHECKED: Joe Lee DRAWN: Y.Liu ERP: 1332000682